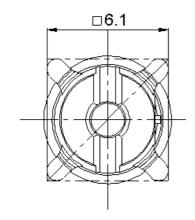
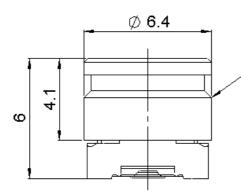
REEL OF 750

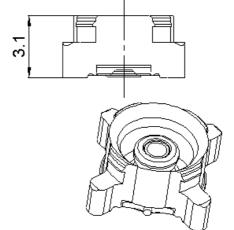
R223.424.800

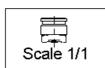
Series: MMBX





Seulement pour conditionnement en bobine. For tape and reel packaging only.





All dimensions are in mm.

			7 +
	COMPONENTS	MATERIALS	PLATING (μm)
•	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BRASS LIQUID CRYSTAL POLYMER PTFE -	NPGR NPGR -

Issue: 0735 C

In the effort to improve our products, we reserve the right to make changes judged to be



REEL OF 750

R223.424.800

Series: MMBX

PACKAGING

Standard	Unit	Other
750	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω

Frequency **0-12.4** GHz **VSWR**

1.065 + **0.0000** x F(GHz) Maxi Insertion loss **0.12** $\sqrt{F(GHz)}$ dB Maxi

100 - F(GHz)) dB Maxi

Voltage rating 330 Veff Maxi Dielectric withstanding voltage 1000 Veff mini

RF leakage

1000 M Ω mini

ENVIRONMENTAL

-55/+155 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

to 6 GHz

Inteface MMBX only up to 2.5GHz

PCB to PCB -45 dB up to 2.5GHz

Mated pair height 6.7mm

MECHANICAL CHARACTERISTICS

Center contact retention

Insulation resistance

Axial force – Mating end 10 N mini Axial force – Opposite end 10 N mini

Torque

NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

0,3050 g Weight

Issue: 0735 C

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RADIALL®

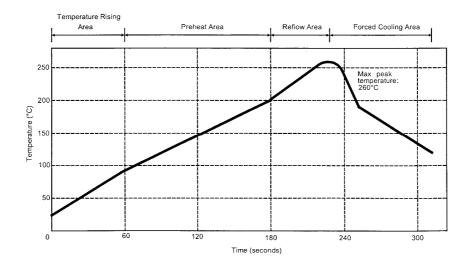
REEL OF 750

R223.424.800

Series: MMBX

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- The cleaning of printed circuit boards is not obliged.
- Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0735 C

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necessary.



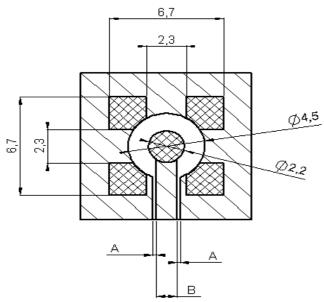
REEL OF 750

R223.424.800

Series: MMBX

MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE

Pattern and signal are on the same side The material of PCB is epoxy resin (FR4). (Er = 4.6)

The solder resist should be printed Except for the land pattern on the PCB



Pattern



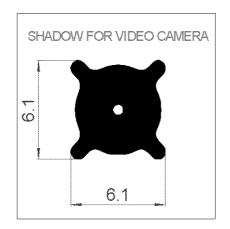
APPLICATION 75 Ω WITH B = 0.55mm

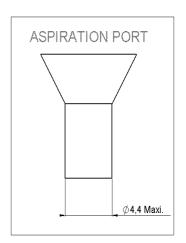
PCB thickness (mm)	Coplanar ligne A (mm)	
0,8	0,350	
1,0	0,360	
1,2	0,365	
1.6	0.375	

APPLICATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1.6	0.210





Issue: 0735 C

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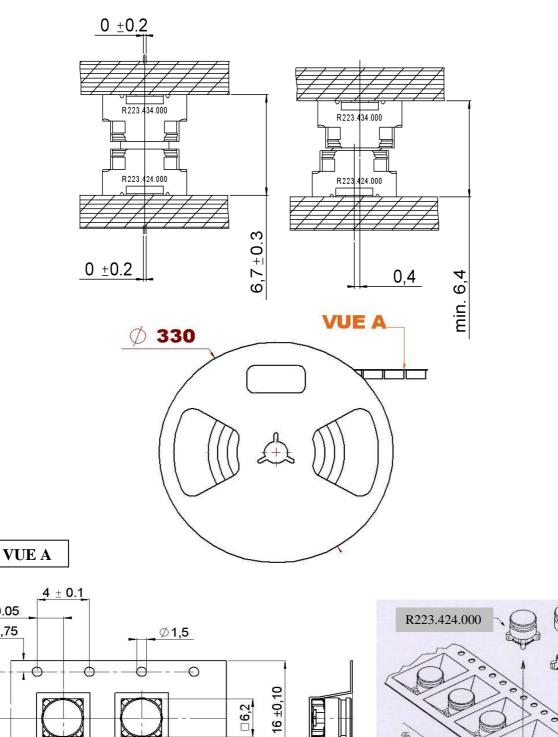


REEL OF 750

R223.424.800

Series: MMBX

INFORMATIONS SUR LA SERIE MMBX



Issue: 0735 C

12 ±0,10

 2 ± 0.05

7,5

1,75

In the effort to improve our products, we reserve the right to make changes judged to be

□6,2

6,3

